

App. No. 10/604,065
Response dated September 28, 2005
Reply to Office Action of June 29, 2005

Please replace pending abstract of the disclosure with the following amended abstract:

ABSTRACT

Wafer holder for semiconductor manufacturing and semiconductor manufacturing device in which the holder is installed, the wafer holder having a wafer-carrying surface, wherein the isothermal rating of its wafer-carrying surface is enhanced. In the wafer holder having a wafer-carrying surface, a shaft that supports the wafer holder is joined to the wafer holder; by making the in-shaft heat capacity of electrodes for supplying power to an electrical circuit formed either on a surface other than the wafer-carrying surface of the wafer holder, or else inside it, 10% or less of the heat capacity of the region of wafer holder that corresponds to the shaft, the temperature distribution in the wafer surface can be brought within an isothermal rating of $[\pm 1.0\%]$ $\pm 1.0\%$. The electrical circuit formed in the wafer holder is preferably at least a resistive heating element.